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(54) Title: SYSTEM AND METHOD FOR HAVING CORRECT-BY-CONSTRUCTION TIMING CLOSURE FOR FACE-TO-FACE BONDING

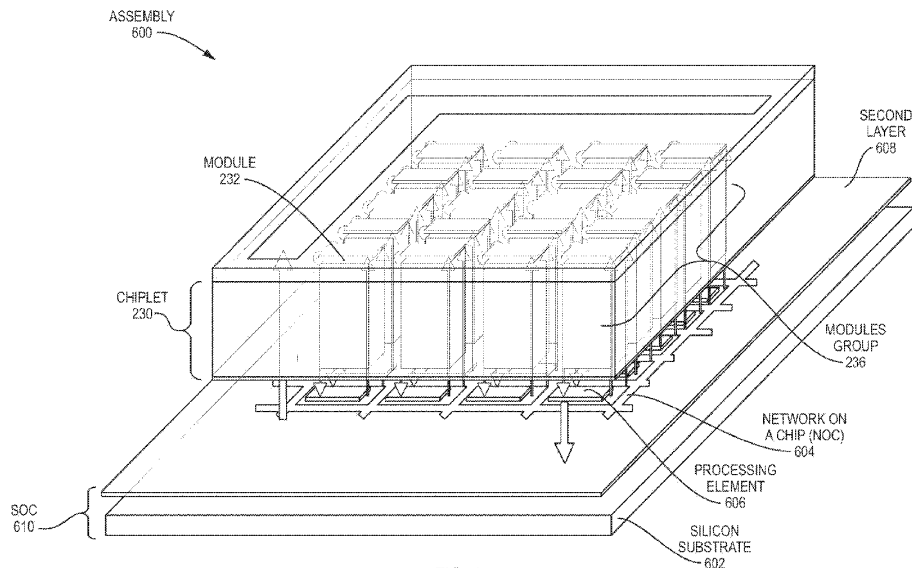


FIG. 6

(57) Abstract: A system, and related method, for achieving correct-by-construction timing closure can comprise a first semiconductor device that provides a thin interface module on a base die, which includes an address registering mechanism for address interconnects in accordance with an address clock from an address-clock interconnect, a data registering mechanism for data interconnects in accordance with a data clock from a data-clock interconnect, and multiple bonding mechanisms for communicating with a second semiconductor device via address and data interconnects.

[Continued on next page]

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